	BLE STAN			9	torage				
	Temperating Temperature Range 2 Voltage Current		2         -55 °C         to         105 °C (i)         Ter           Signal Contact : 50 V AC         Stop         Stop         Stop           Power Contact : 200 V AC         Stop         Stop         Stop		Femperature Range -10 °C to		-10 °C to 6	0 °C	(2)
Rating							-	elative humidity 85% max	
			SPEC	IFICATION	٧S				
ITI	EM		TEST METHOD			REQU	IREMENTS	QT	A
CONSTRU	JCTION				•				
General Examination		Visually and by measuring instrument.			According to drawing.			×	>
Marking		Confirmed visually.						×	;
ELECTRIC CHARAC									
Contact Resistance		100 mA(DC or 1000Hz)			Signal Contact : $70m \Omega$ MAX. Power Contact : $20m \Omega$ MAX.			×	-
Insulation Resistance		Signal Contact : 100 V DC. Power Contact : 250 V DC			Signal Contact : 100 M $\Omega$ MIN. Power Contact : 1000 M $\Omega$ MIN.			×	-
Voltage Proof		Signal Contact : 150 V AC for 1 min.			No flashover or breakdown.			×	>
		Power Contact : 600 V AC for 1 min.			ino nas				-
	CAL CHAR								
Insertion and		Measured by applicable connector.				Insertion Force: 27 N MAX.			-
Withdrawal Forces		100 times insertions and sutrasticut				Withdrawal Force: 3 N MIN.			+
Mechanical Operation		100 times insertions and extractions.			<ol> <li>Contact Resistance: Signal Contact : 80m Ω MAX. Power Contact : 30m Ω MAX.</li> <li>No damage, crack and looseness of parts.</li> </ol>			×	-
Vibration		Frequency 10 to 55 to 10Hz, approx 5min Single amplitude : 0.75 mm, 10 cycles			1) No	<ol> <li>No electrical discontinuity of 1 μs.</li> <li>No damage, crack and looseness of parts.</li> </ol>			-
Shock		for 3 axial directions. 490 m/s <sup>2</sup> , duration of pulse 11 ms				-		×	-
			or 3 both axial directions.						
	MENTAL C							-	
Damp Heat (Steady state)		Exposed at 40±2 °C, 90 ~ 95 %, 96 h.			① Contact Resistance: Signal Contact : 80m Ω MAX.			×	-
Rapid Change of Temperature		Temperature $-55 \rightarrow +85 \text{ °C}$ Time $30 \rightarrow 30$ min.			Power Contact : 30m Ω MAX. ② Insulation Resistance: Signal Contact : 100 MΩ MIN.			×	-
		under 5 cycles. (Relocation time to chamber : within 2~3 MIN)			F	Power Contact	:: 1000 MΩ MIN.		
Cold		Exposed at -55°C, 96 h			③ No damage, crack and looseness of parts.         ① Contact Resistance:         Signal Contact :       80m Ω MAX.			×	-
Dry Heat		Exposed at 105°C, 96 h						×	-
Sulfur Dioxide		Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h. (Test standard: IEC 68)			<ol> <li>No defect such as corrosion which impairs the function of connector.</li> <li>Contact Resistance: Signal Contact : 80m Ω MAX. Power Contact : 30m Ω MAX.</li> </ol>			×	+ -
Resistance to		1)Reflow soldering :			No deformation of case of excessive			×	1-
Soldering Heat		Peak TMP : 260°CMAX Reflow TMP: 220°CMIN for 60sec			loosene	looseness of the terminal.			
<u></u>			g irons : 360°C MAX. for 5	sec.	<u> </u>			×	
Solderability		Soldered at solder temperature $240\pm3^{\circ}$ C for immersion duration, 3 sec.			minimu	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.			-
COUN	זח ד	- ESCRIPTION	N OF REVISIONS	DESI	GNED		CHECKED		
0000			-00002065	-	ONED		HT. YAMAGUCHI	17.0	
A 2	<sup>1</sup> Include temperature rise caused by current-carrying.		13.		APPROVED HS. OKAWA		14.0		
2 REMARKS (	<ul> <li>(2) "STORAGE" means a long-term storage state for the unused product before assembly to PCB.</li> </ul>					CHECKED	KN. SHIBUYA	14.09.0	
REMARKS		ly to PCB.			DESIGNED		TS. 00N0	14.09.0	
REMARKS (	before assembl								
Unless othe	before assembl erwise speci	fied, refer to	o IEC 60512.	I		DRAWN	TS. 00N0	14.0	
Unless othe	before assemblerwise speci ualification Tes	fied, refer to st AT:Assu	o IEC 60512. rance Test X:Applicable Te XATION SHEET		DRAWIN T NO.	IG NO.		14.0	